

Claims

- 1 1. A device package, comprising:
2 a conductive substrate having a bottom side defining a footprint of the device package
3 and having a top side with at least one mounting site;
4 an insulating substrate with a first side on the top side of the conductive substrate, the
5 insulating substrate having at least one aperture providing access between a second side of
6 the insulating substrate and the at least one mounting site, the insulating substrate having one
7 or more signal paths on the second side coupling the at least one aperture to one or more
8 contact sites disposed about the insulating substrate; and
9 a series of conductive tabs, each of the conductive tabs coupled to a corresponding
10 one of the one or more contact sites.

- 1 2. The device package of claim 1 further comprising at least one optical device
2 mounted at the at least one mounting site.

- 1 3. The device package of claim 2 wherein the at least one optical device includes at
2 least one of an LED, photodetector and laser diode.

- 1 4. The device package of claim 3 further comprising an encapsulant covering the at
2 least one aperture on the second side of the insulating substrate.

1 5. The device package of claim 1 wherein the conductive tabs are gull-wings disposed
2 about the periphery of the conductive substrate.

1 6. The device package of claim 2 wherein the conductive tabs are gull-wings disposed
2 about the periphery of the conductive substrate.

1 7. The device package of claim 3 wherein the conductive tabs are gull-wings disposed
2 about the periphery of the conductive substrate.

1 8. The device package of claim 4 wherein the conductive tabs are gull-wings disposed
2 about the periphery of the conductive substrate.

1 9. The device package of claim 1 wherein the conductive tabs are posts that penetrate
2 the conductive substrate.

1 10. The device package of claim 2 wherein the conductive tabs are posts that
2 penetrate the conductive substrate.

1 11. The device package of claim 3 wherein the conductive tabs are posts that
2 penetrate the conductive substrate.

1 12. The device package of claim 4 wherein the conductive tabs are posts that
2 penetrate the conductive substrate.

1 13. The device package of claim 1 wherein one or more of the one or more
2 conductive tabs are grounded to the conductive substrate.

1 14. The device package of claim 2 wherein one or more of the one or more
2 conductive tabs are grounded to the conductive substrate.